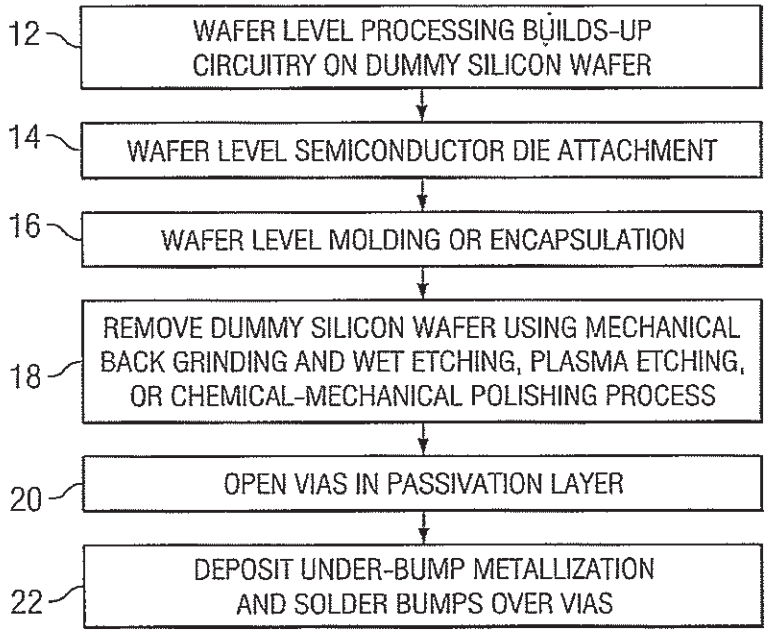

12
WAFER LEVEL PROCESSING BUILDS-UP CIRCUITRY ON DUMMY SILICON WAFER
14
WAFER LEVEL SEMICONDUCTOR DIE ATTACHMENT
16
WAFER LEVEL MOLDING OR ENCAPSULATION
18
REMOVE DUMMY SILICON WAFER USING MECHANICAL BACK GRINDING AND WET ETCHING, PLASMA ETCHING, OR CHEMICAL-MECHANICAL POLISHING PROCESS
20
OPEN VIAS IN PASSIVATION LAYER
22
DEPOSIT UNDER-BUMP METALLIZATION AND SOLDER BUMPS OVER VIAS

FIG. 1

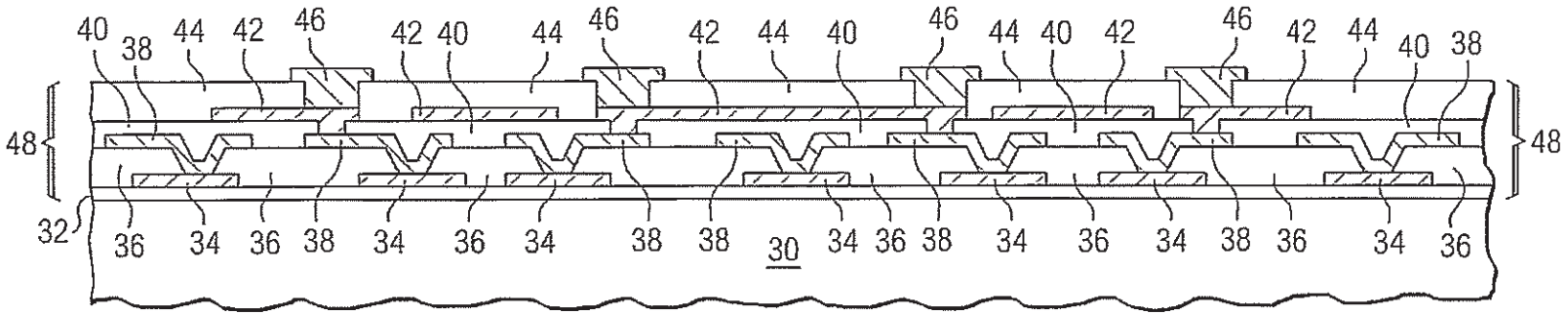

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FIG. 2a

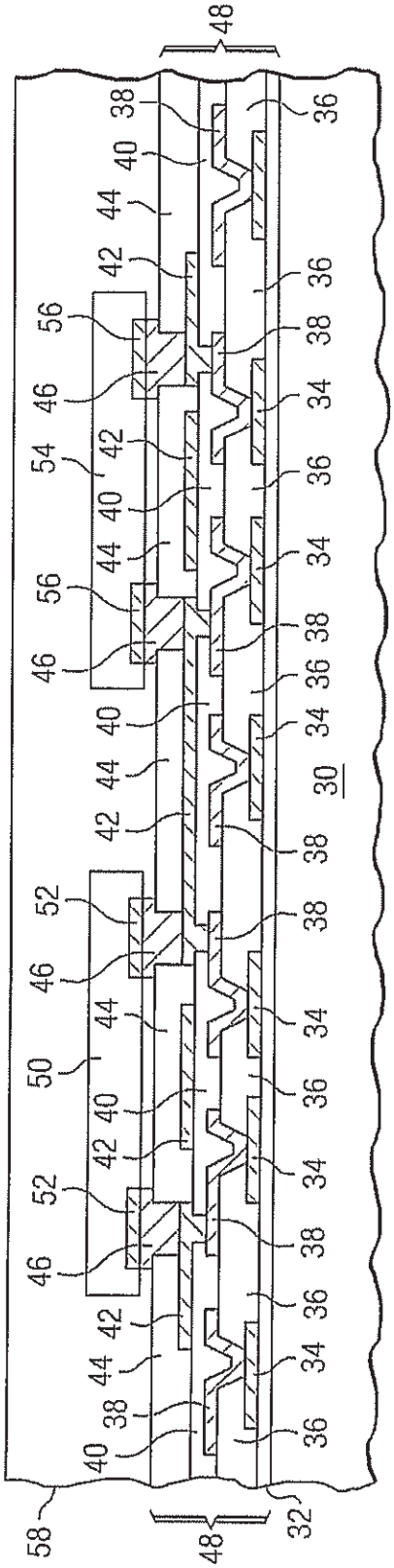


FIG. 2b

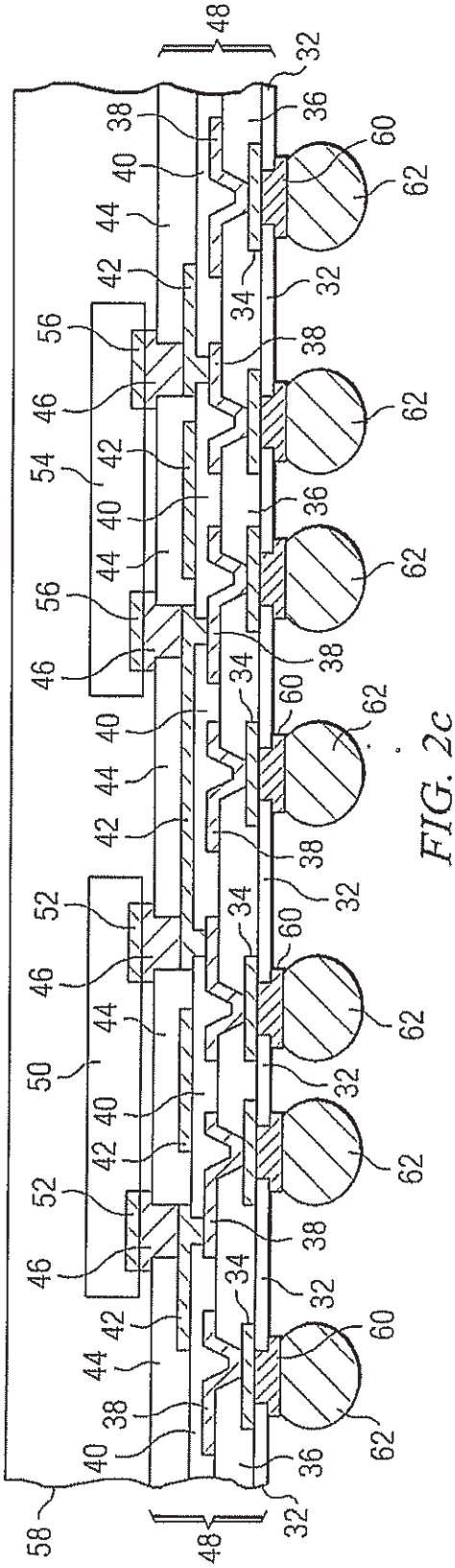


FIG. 2c

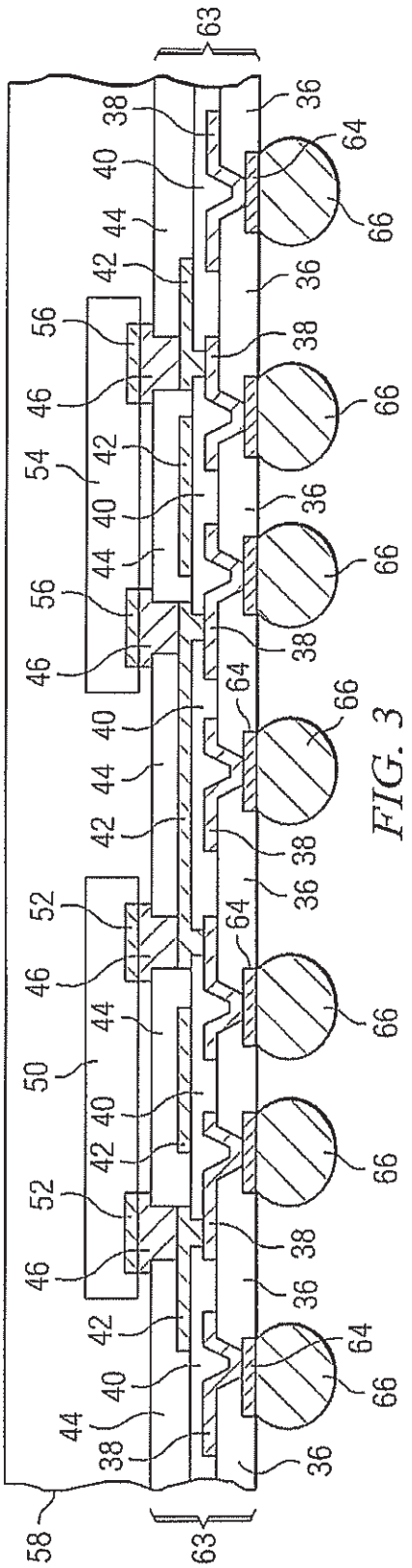

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FIG. 3

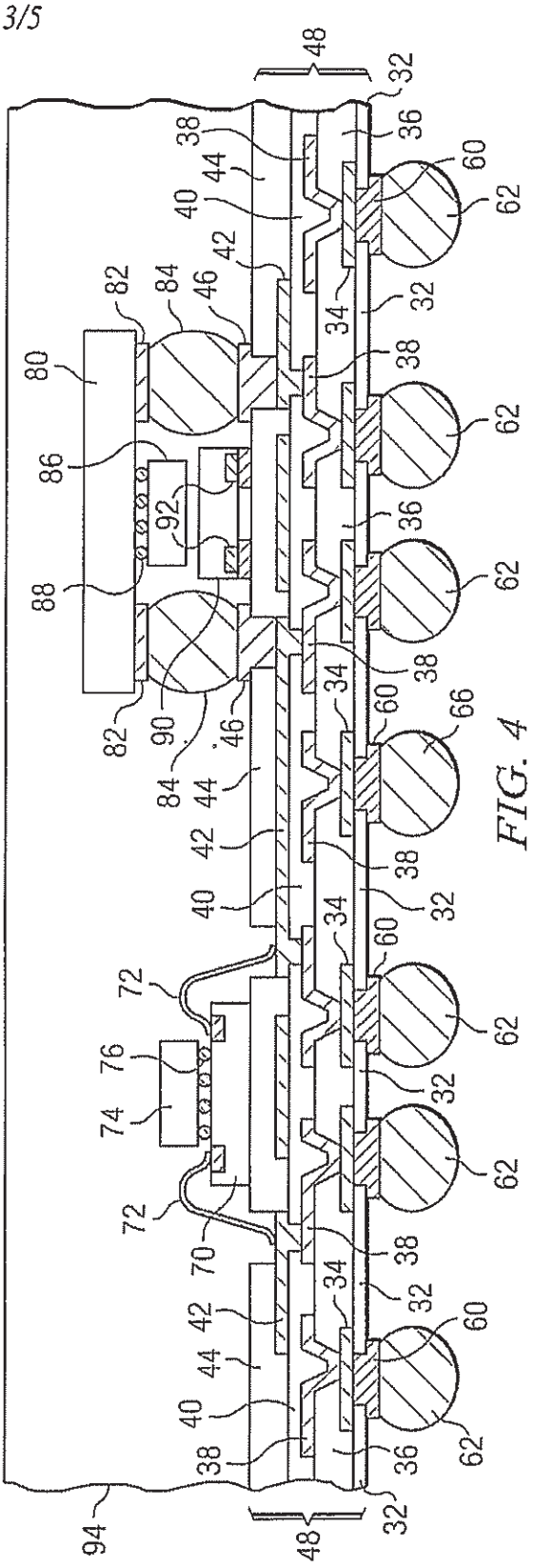

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FIG. 4

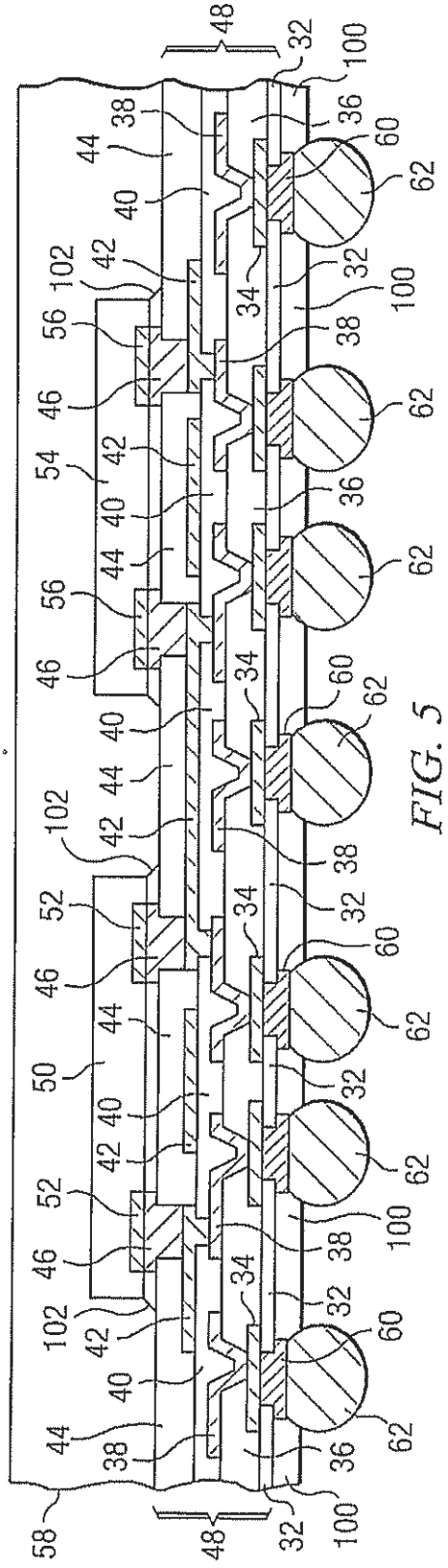

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FIG. 5

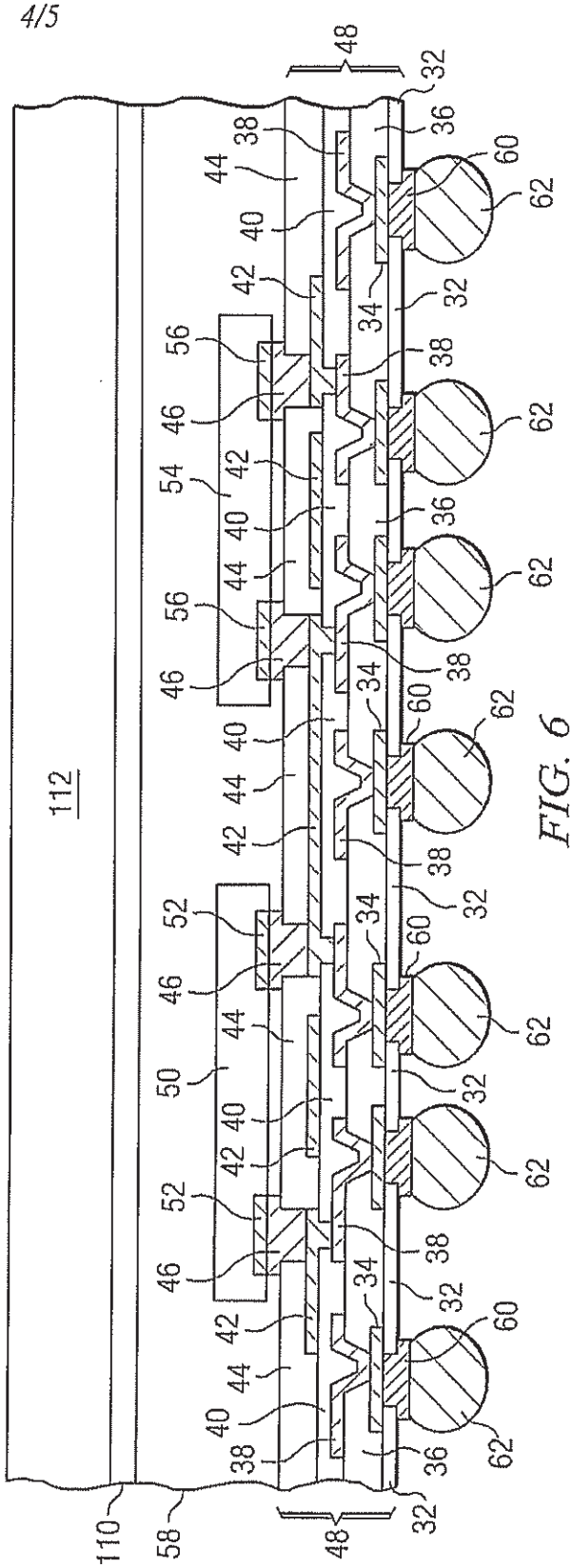

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FIG. 6

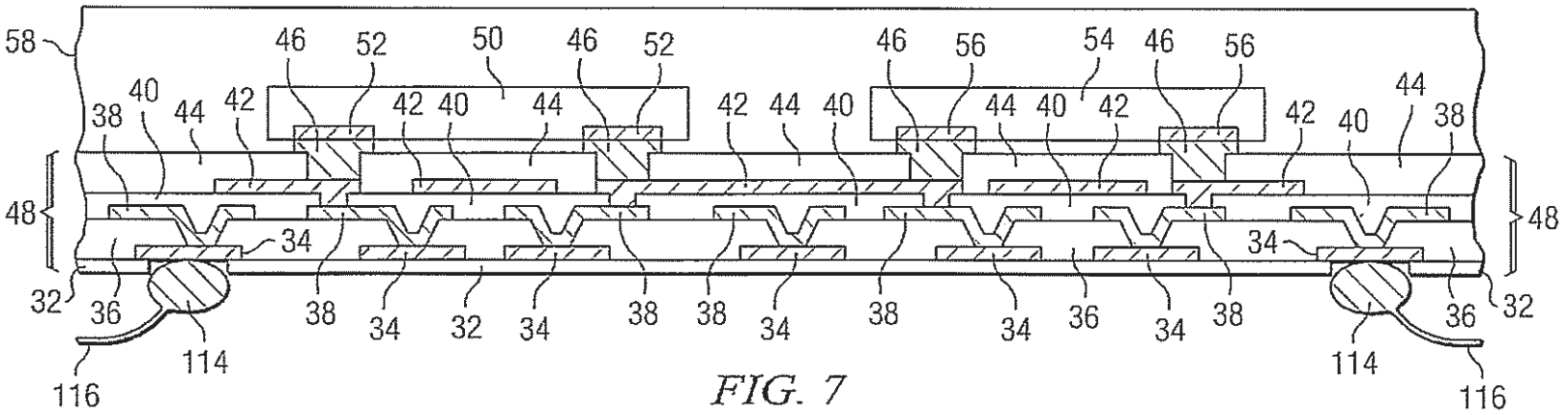

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FIG. 7

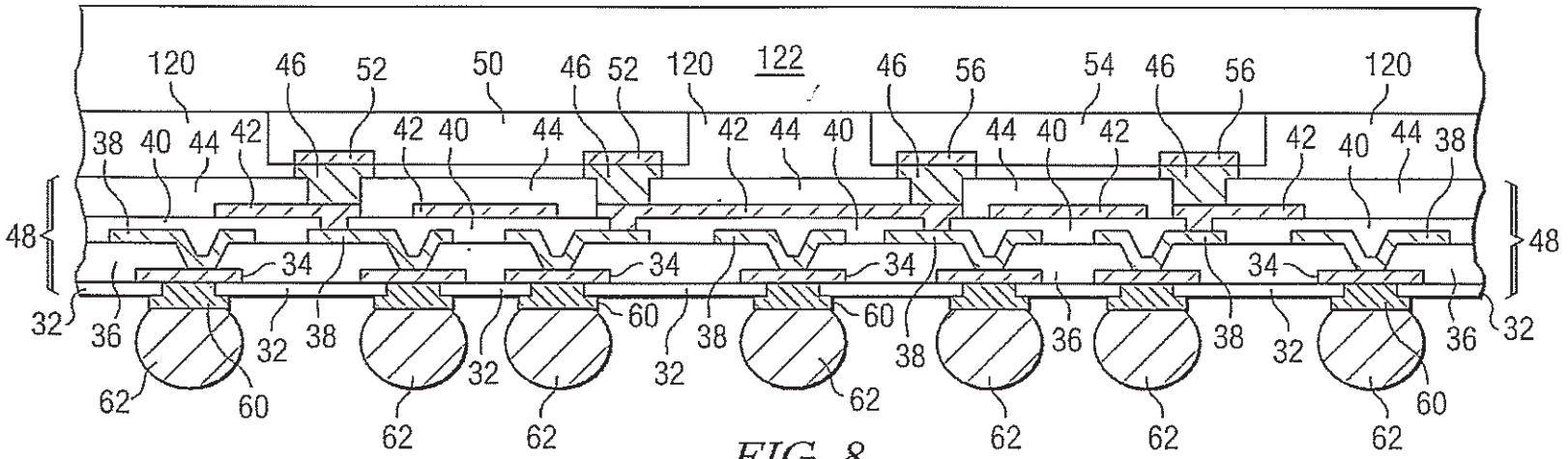

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FIG. 8